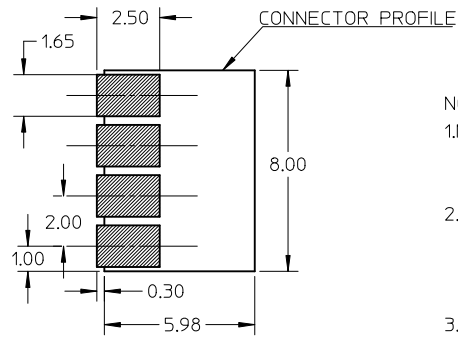
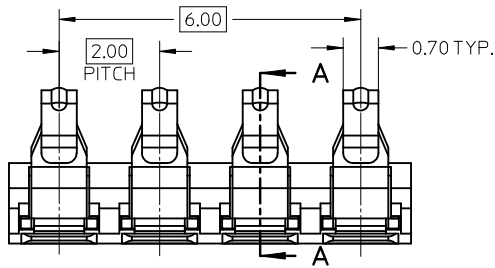
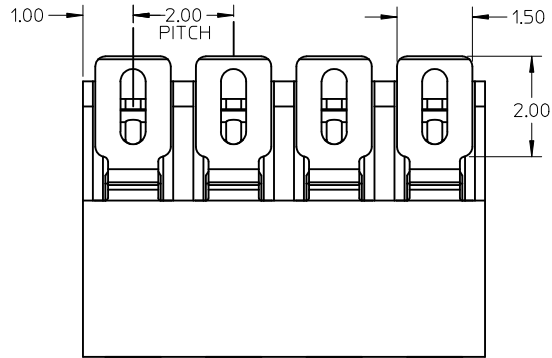


SECTION A-A



RECOMMENDED PCB LAYOUT



NOTE:

1.MATERIAL:

HOUSING: HIGH TEMPERATURE THERMOPLASTIC,COLOR:BLACK
 TERMINAL: COPPER ALLOY

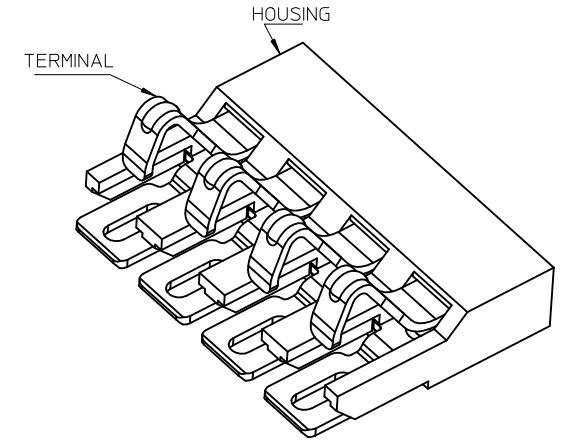
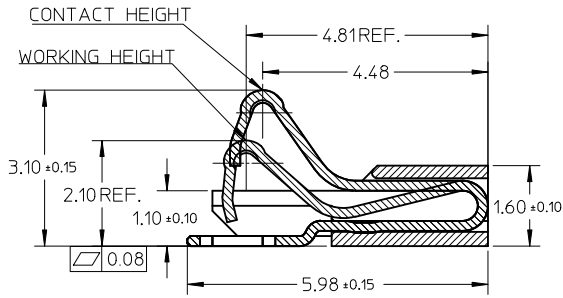
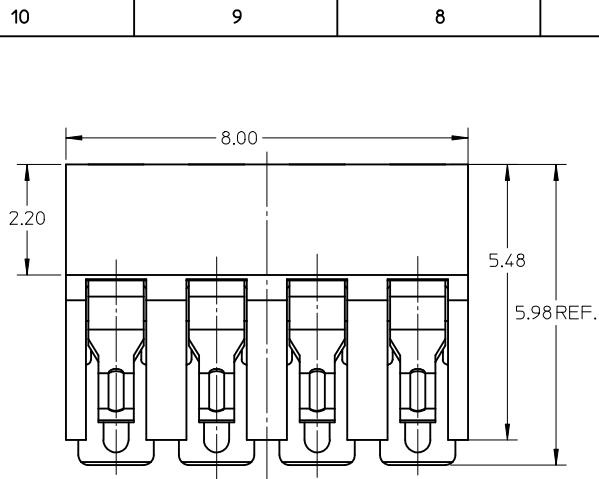
2.FINISH:

CONTACT AREA: 0.75 MICRON GOLD MIN OVER 1.25 MICRON NICKEL MIN.
 SOLDER AREA: GOLD FLASH (0.075 ~ 0.125 MICRON) OVER 1.25 MICRON NICKEL MIN.
 REST AREA: 1.25 MICRON NICKEL MIN.

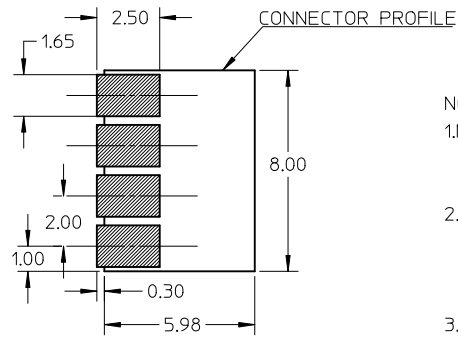
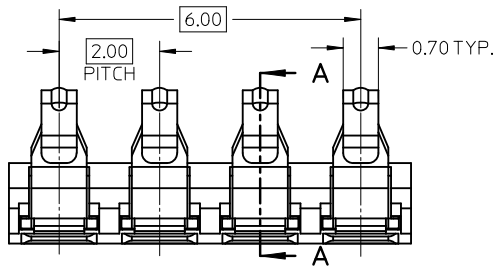
3.PRODUCT SPECIFICATION: PS-47359-001

4.WORKING HEIGH: 2.10MM COUNTED FROM TOP OF PCB.

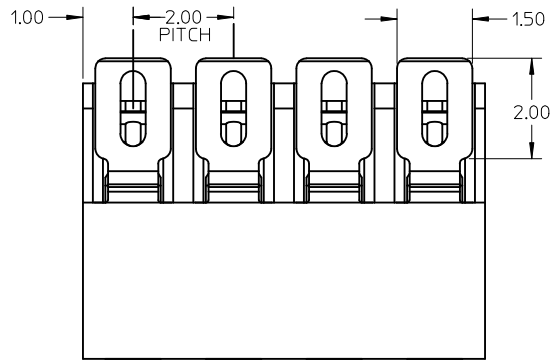
REVISED EC NO: S2011-0103 DRWN:SHONG 2010/08/04 CHKD:LING 2010/09/20 APPR: NAGESHKN 2010/09/22	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION															
	$\nabla=0$ $\triangle=0$	<table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.13</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± 0.20</td> <td>± ---</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.13	± ---	1 PLACE	± 0.20	± ---	MM ONLY	5:1	METRIC	
		mm	INCH																		
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$\nabla=0$ $\triangle=0$	ANGULAR ± 1 °	DRAWN BY LSHEN CHECKED BY XU XIANG APPROVED BY JENNY CHEN MATERIAL NO. 473590001	DATE 2005/11/18 DATE 2006/06/13 DATE 2006/06/13	TITLE	2.0MM PITCH 4 CIRCUITS 0.7MM CONTACT WIDTH BATTERY CONNECTOR																
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	MOLEX MOLEX INCORPORATED DOCUMENT NO. SD-47359-001	SHEET NO. 1 OF 1															



SECTION A-A



RECOMMENDED PCB LAYOUT



NOTE:

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REVISED EC NO: S2011-0103 DRWN:SHONG 2010/08/04 CHKD:LING 2010/09/20 APPR: NAGESHKN 2010/09/22	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.13 ± --- 1 PLACE ± 0.20 ± --- ANGULAR ± 1 °	DIMENSION STYLE MM ONLY DRAWN BY DATE LHSNEN 2005/11/18 CHECKED BY DATE XU XIANG 2006/06/13 APPROVED BY DATE JENNY CHEN 2006/06/13 MATERIAL NO. 473590001	SCALE 5:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE 2.0MM PITCH 4 CIRCUITS 0.7MM CONTACT WIDTH BATTERY CONNECTOR MOLEX INCORPORATED DOCUMENT NO. SD-47359-001	SHEET NO. 1 OF 1
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
	SIZE A3					